

Best Available Copy



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re Application of:

Kling, et al.

Application No: 09/974,023

Filed: October 10, 2001

For: *Embedded Capacitor Multi-Chip Modules*

Conf. No.: 7890

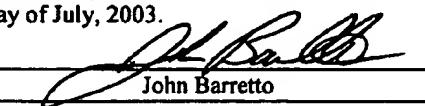
Art Unit: 2814

Examiner: Hoai Pham

Atty. Docket: RAK-001.02

CERTIFICATE OF FIRST CLASS MAILING

I hereby certify that the foregoing documents are being deposited with the United States Postal Service as First Class Mail, postage prepaid, in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313, on this 25th day of July, 2003.



John Barretto

TECHNICAL CENTER 2800
AUG - 1 2003

SUBMISSION OF FORMAL DRAWINGS

Commissioner for Patents
PO Box 1450
Alexandria, VA 22313

Attn: Official Draftsperson

Sir:

Applicant hereby submits three (4) sheets of formal drawings containing Figs. 1-7 for the above-referenced application.

Should there be any questions after reviewing this paper, the Examiner is invited to contact the undersigned at 617-832-1175.

Respectfully Submitted,



Robert W. Gauthier
Reg. No. 35,153

Date: July 25, 2003

Customer No: 25181

Patent Group

Foley Hoag LLP

155 Seaport Blvd.

Boston, MA 02210-2600